

Title (en)

Electrolytic Tin Plating Solution and Electrolytic Tin Plating Method

Title (de)

Elektrolytische Zinnbeschichtungslösung und elektrolytisches Zinnbeschichtungsverfahren

Title (fr)

Solution électrolytique de placage d'étain et procédé électrolytique de placage d'étain

Publication

EP 2141261 B1 20170301 (EN)

Application

EP 09155197 A 20090316

Priority

JP 2008154461 A 20080612

Abstract (en)

[origin: EP2141261A2] A plating solution and a plating method, which does not use a complexing agent and which provides favorable solder wetting properties and an extremely low coupling rate when electrolytic tin plating is performed, and particularly when electrolytic tin plating is performed using a barrel plating method.

IPC 8 full level

C25D 3/30 (2006.01); **C25D 7/12** (2006.01); **C25D 17/16** (2006.01)

CPC (source: EP KR US)

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Cited by

EP3715508A4; EP2740820A1; WO2019201753A1; US11242606B2; US11840771B2; WO2019121092A1; US11459665B2

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